

## NC722 Low Melting No-Clean Lead-Free Solder Paste

### Introduction

NC722 solder paste is a low melting no-clean lead-free solder paste with pin-testable flux residue formulated for use with tin-bismuth alloys. NC722 is an excellent choice for applications which require reflow temperatures below that of standard lead-free alloys. NC722 is also halide and halogen free (zero halogens).

### Attributes

- Low melting lead-free solder paste based on tin/bismuth alloys.
- Clear, pin-testable flux residue.
- Halide and halogen free. No intentionally added halogens (Zero halogens).

Solder Alloy	Solder Powder Size Availability (IPC J-STD-005)	Melting Range (°C)
Sn42/Bi58	Type 3	138°C
Sn42/Bi57/Ag1	Type 3	138 - 140°C

- Other sizes of solder powder are available upon request.
- The size range for the solder powder types are as follows:
  - Type 3 (25-45 µm >80%). Mesh -325/+500
  - Type 4 (20-38 µm >80%). Mesh -400/+635
  - Type 5 (15-25 µm >80%). Mesh -500/+800

Solder Paste Packaging	Net Weight (grams)
Jars	250, 500
Cartridges	500 or 600 (6 oz), 700 (8 oz), 1300 (12 oz)
Syringes	30, 100
Enclosed print systems	800

### Compatible Products

NC120, NC160, NC165 liquid fluxes.  
NC26 gel flux.

### Storage and Handling

- Shelf life is 6 months when stored at 0 to 10 °C (32 to 50 °F).
- Accidental warming of solder paste above 29 °C (85 °F) for a period of time can cause detrimental effects.
- Warm the solder paste to room temperature before use. Do not force warming by heating the solder paste. Keep the solder paste sealed while warming. Warming typically takes 3 to 4 hours when the solder paste is sitting at room temperature.

- Once the solder paste container is opened then the solder paste should be kept at room temperature only during use. Unused solder paste should be sealed in the original container and stored in a cooler until needed.
- Solder paste used in the print process should not be added to a container with fresh solder paste. This will change the rheology of the fresh solder paste. Solder paste used on the printer can be stored in a separate container at room temperature. Used solder paste can be reused but print and reflow characteristics will degrade over time.
- After printing, the solder paste should be reflowed within a normal processing time. The maximum allowable time between print and reflow is 4 hours.

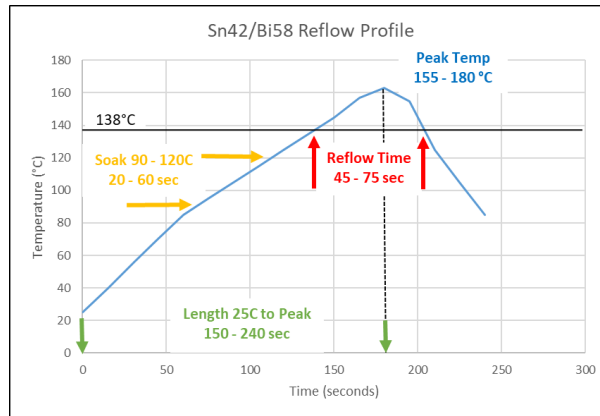
Print Parameter	Preferred	Acceptable
Solder paste bead size	1.5 to 2.0 cm (0.60 to 0.80 in)	1.0 to 2.5 cm (0.40 to 1.0 in)
Squeegee blade	Fine grain stainless steel. 60° from horizontal. 45° from horizontal for pin in paste.	Any type of stainless steel
Stencils	Fine grain (2-5 µm) or ultra-fine grain (1-2 µm) stainless steel	All types of commercially available stencils
Print speed	30 to 100 mm/sec (1.2 to 4.0 in/sec)	20 to 200 mm/sec (0.8 to 8.0 in/sec)
Pressure / blade length (increase with increasing speed)	0.18 to 0.27 kg/cm (1.0 to 1.5 lbs/in)	0.18 to 0.54 kg/cm (1.0 to 3.0 lbs/in)
Separation speed	1.0 to 5.0 mm/sec	0.5 to 10.0 mm/sec
Underside stencil cleaning	Wet / vacuum / vacuum cycle every 1-5 prints	Other cleaning cycles every 1 to 20 prints depending upon technology
Stencil life	4 hours at 18-29 °C (65-85 °F) and 10-70% RH.	Stencil life may be shorter outside of the preferred conditions.

- Blade pressure should be set as low as possible to clean off the stencil. Higher blade pressures will increase stencil and blade wear, and can lead to “scooping” and other print defects.
- Underside stencil cleaning is best accomplished with commercial cleaners and high quality wipe materials. Nano-coated stencils can be used to reduce the frequency of underside cleaning.

Reflow Parameter	Preferred	Acceptable
Profile length (25 °C to peak)	2.5 to 3.5 min (150 to 210 sec)	2.5 to 4.0 min (150 to 240 sec)
Heating ramp rate maximum (20 second window)	2.0 °C/sec max	3.0 °C/sec max
Preheat / soak time (90 - 120 °C)	20 to 40 sec	20 to 60 sec
Peak temperature	155 to 175 °C	155 to 180 °C
Reflow time (time above liquidus)	50 to 70 sec	45 to 75 sec
Cooling ramp rate minimum (20 second window)	4.0 °C/sec min	2.0 °C/sec min

- Reflow time should be calculated based on the liquidus point of the alloy used: Sn42/Bi58 = 138°C, Sn42/Bi57/Ag1 = 140°C.

An example reflow profile graph is shown below. This is a good starting point but it can be modified to fit the product and process. Contact FCT Assembly for assistance with reflow profiling.



Sn/Bi alloys should not be mixed with lead (Pb) bearing metals. If Pb is mixed with Sn and Bi, then a very low melting (approx. 95 °C) intermetallic compound can form. This very low melting Sn/Bi/Pb compound may cause solder joint failure due to heating during operation of the electronics.

**Cleaning**

Raw solder paste can be removed from the stencil, squeegee blades, and circuit boards using a variety of commercial cleaners. Isopropyl alcohol (IPA) can also be used.

After reflow, no-clean solder paste residues are designed to be “safe” and do not need to be removed from the circuit board. If removal of the flux residues is desired, then a commercial cleaning agent should be used. Several common cleaning agents have been tested and found to be effective. Please contact your cleaning chemical supplier for details.

**Safety**

Wear chemically resistant gloves when handling solder paste. Avoid breathing fumes, especially during reflow of the solder paste. Follow the guidelines detailed in the Safety Data Sheet (SDS).

J-STD-004 Flux Standard	Test Method	Result
J-STD-004 classification	J-STD-004 methods	ROLO
Halide ion content (Br <sup>-</sup> , Cl <sup>-</sup> , F <sup>-</sup> , I <sup>-</sup> )	IPC 2.3.28.1	0.0 % wt
Halogen content (Br and Cl)	EN 14582, IPC 2.3.28.1	0.0 % wt
Halide by silver chromate	IPC 2.3.33	No halides detected
Fluoride by spot test	IPC 2.3.35.1	None detected
Copper mirror	IPC 2.3.32	Low activity
Copper corrosion	IPC 2.6.15	No corrosion

Surface Insulation Resistance (SIR)	IPC 2.6.3.7	Pass
Electro Chemical Migration (ECM)	IPC 2.6.14.1	Pass
<b>J-STD-005 Solder Paste Standard</b>	<b>Test Method</b>	<b>Result</b>
Viscosity - Brookfield	IPC 2.4.34	520 - 620 Kcps typical
Slump - frosted glass	IPC 2.4.35	Pass
Solder balling - frosted glass	IPC 2.4.43	Acceptable
Wetting - copper	IPC 2.4.45	Pass
Tack force	IPC 2.4.44	30 gram force typical